



Publications/Presentations for Scott A. Merritt

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The Iterated Extended Kalman Phase Detector

IEEE Transactions on Communications, Volume: 37 Issue: 5 , May 1989, pp. 522 -526

Angle Dependence of Facet Reflectivity in Semiconductor Traveling Wave Amplifiers

CLEO-93, May 2-7, 1993, Baltimore Md, Ctu-N6

Etch Characteristics of Succinic Acid/Ammonia/Hydrogen Peroxide versus Aluminum Mole Fraction in AlGaAs

J. Electrochem. Soc., Vol. 140, No. 9, Sept 1993, pp. L138-L139

Angled-Facet High Power Diffraction Limited Tapered Semiconductor Amplifier

LEOS-94

Self-Aligned Dissipating Grid for High-Power Tapered Semiconductor Amplifiers

Conference on Lasers and Electro-Optics, CLEO-94

Measurement of the Facet Modal Reflectivity Spectrum in High Quality Semiconductor Traveling Wave Amplifiers

Lightwave Technology, Journal of , Volume: 13 Issue: 3 , March 1995 Page(s): 430 –433

Single-Angled-Facet Laser Diode for Tunable External Cavity Lasers

Sarnoff Symposium, 1995., IEEE Princeton Section , April 28,1995 Page(s): 0_130 -0_132

A Reliable Die Attach Method for High Power Semiconductor Lasers and Optical Amplifiers

Electronic Components and Technology Conference, 1995. Proceedings., 45th , 21-24 Page(s): 428 –430

GaAs-AlGaAs QW Diluted Waveguide Laser with Low-Loss, Alignment-Tolerant Coupling to a Single-Mode Fiber

Photonics Technology Letters, IEEE , Volume: 8 Issue: 9 , Sept. 1996 Page(s): 1130 –1132

Wet-Chemistry Surface Treatment for Dark-Current Reduction that Preserves Lateral Dimensions of Reactive Ion Etched Ga_{0.47}In_{0.53}As P-I-N Diode Photodetectors

Photonics Technology Letters, IEEE , Volume: 9 Issue: 4 , April 1997 Page(s): 490 –492

A Rapid Flip Chip Die Bonding Method for Semiconductor Laser Diode Arrays

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Controlled Solder Interdiffusion for High Power Semiconductor Laser Diode Die Bonding

Components, Packaging, and Manufacturing Technology, Part B: Advanced Packaging, IEEE Transactions on [see also Components, Hybrids, and Manufacturing Technology, IEEE Transactions on] , Volume: 20 Issue: 2 , May 1997 Page(s): 141 –145

Polarization Insensitive 1.55 μm Optical Amplifier with GaAs Delta-Strained Ga_{0.47}In_{0.53}As Quantum Wells

Lasers and Electro-Optics Society Annual Meeting, 1997. LEOS '97 10th Annual Meeting. Conference Proceedings., IEEE , Volume: 1, 10-13 Nov. 1997, pp. 335 -336

Design of a 40 Gbps WDM Laser Module

Vertical-Cavity Lasers, Technologies for a Global Information Infrastructure, WDM Components Technology, Advanced Semiconductor Lasers ..., Gallium Nitride Materials, Processing, ..., 1997 Digest of the IEEE/LEOS Summer Topical Meetings , 11-15 Aug. 1997 Page(s): 66 –67



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Polarization Insensitive 1.55- μm Optical Amplifier with GaAs Delta-Strained $\text{Ga}_{0.47}\text{In}_{0.53}\text{As}$ Quantum Wells

Photonics Technology Letters, IEEE , Volume: 9 Issue: 10 , Oct. 1997 Page(s): 1340 –1342

A Low-Cost Electroless Plating Method for Producing Flip-Chip Bondable and Wire-Bondable Circuit Pads for Smart Pixel Application

Lasers and Electro-Optics Society Annual Meeting, 1998. LEOS '98. IEEE , Volume: 1 , 1-4 Dec. 1998 Page(s): 99 -100 vol.1

Electroless Remetallization of Aluminum Bond Pads on CMOS Driver Chip for Flip-Chip Attachment to Vertical Cavity Surface Emitting Lasers (VCSEL's)

Components and Packaging Technologies, IEEE Transactions on [see also Components, Packaging and Manufacturing Technology, Part A: Packaging Technologies, IEEE Transactions on] , Volume: 22 Issue: 2, June 1999 Page(s): 299 –306

Optoelectronic Packaging ,

Edited by Alan R. Mickelson, Nagesh R. Basavanthally, and Yung-Cheng Lee , *John Wiley & Sons, Chapter 5 by S.A. Merritt, K. Mobarhan, M.Dagenais, S. Fox, R. Whaley,*